

William R Eisenstadt

List of Publications by Year in descending order

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36
papers

193
citations

1163117

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1125743

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36
docs citations

36
times ranked

184
citing authors

#	ARTICLE	IF	CITATIONS
1	Wirelessly triggered bioactive molecule delivery from degradable electroactive polymer films. <i>Polymer International</i> , 2021, 70, 467-474.	3.1	17
2	Testing and Validation of Adaptive Impedance Matching System for Broadband Antenna. <i>Electronics (Switzerland)</i> , 2019, 8, 1055.	3.1	3
3	Structural parameters effect on signal integrity of inter-tier vias in 3D stacking technology. , 2018, , .		0
4	Guest Editorial: Analog, Mixed-Signal and RF Testing. <i>Journal of Electronic Testing: Theory and Applications (JETTA)</i> , 2017, 33, 281-282.	1.2	1
5	A 6 pJ/bit transmitter front end in 130 nm CMOS technology for wireless interconnect. , 2015, , .		1
6	Low-power wireless climate monitoring system with RFID security access feature for mosquito and pathogen research. , 2015, , .		7
7	True-differential/common-mode mixed-mode S-parameter measurement techniques for cellular and 4G bandwidths. , 2015, , .		0
8	Automated wideband test system, measurement uncertainty, and design of on-chip six-port reflectometers for 5G applications. , 2015, , .		4
9	Progress in development of the low-power wireless multiple temperature sensor pole for pesticide, agriculture, and mosquito research. , 2015, , .		1
10	CMOS Broadband Programmable Gain Active Balun With 0.5-dB Gain Steps. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2015, 63, 2650-2660.	4.6	2
11	Polarization Differential Antenna for LOS Communications in a Multi-Antenna System. <i>IEEE Transactions on Antennas and Propagation</i> , 2014, 62, 3978-3984.	5.1	1
12	Signal integrity characterization of high-speed I/O in 3D chip-package system. , 2013, , .		0
13	Tunable Broadband MMIC Active Directional Coupler. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2013, 61, 168-176.	4.6	16
14	Characterization of embedded RF elements on a 3D integrated circuit. , 2013, , .		0
15	Cost effective modeling methodologies and evaluating electrical interaction in FCBGA packages. , 2013, , .		0
16	Embedded RF Test Circuits: RF Power Detectors, RF Power Control Circuits, Directional Couplers, and 77-GHz Six-Port Reflectometer. <i>Journal of Information and Communication Convergence Engineering</i> , 2013, 11, 56-61.	0.2	15
17	GTL high speed I/O in 3D ICs for TSV and interconnect signal integrity characterization. , 2012, , .		2
18	Design and packaging of small 60 GHz antenna array for multi-chip communication. , 2012, , .		2

#	ARTICLE	IF	CITATIONS
19	CMOS Programmable Gain Distributed Amplifier With 0.5-dB Gain Steps. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 1552-1559.	4.6	13
20	A sub-1V CMOS voltage reference generator. , 2011, , .		1
21	Software Defined Match Control Circuit Integrated With a Planar Inverted F Antenna. IEEE Transactions on Antennas and Propagation, 2010, 58, 3884-3890.	5.1	16
22	A wide-band differential and single-ended microwave amplitude detector. , 2010, , .		2
23	Design of compact adaptive RF matching circuits using Square split ring resonators. , 2010, , .		0
24	On-chip S<inf>11</inf> signal detection circuit. , 2009, , .		1
25	High speed I/O and thermal effect characterization of 3D stacked ICs. , 2009, , .		4
26	Evaluation of Measurement Uncertainties Caused by Common and Cross Modes in Differential Measurements Using Baluns. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1485-1492.	4.6	4
27	Design of Multigigabit-per-Second Transceiver for Band-Limited High-Speed Data Communication Using DC-Free Signaling. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1555-1564.	4.6	1
28	Broadband Active Balun Using Combined Cascade" Cascade Configuration. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1790-1796.	4.6	35
29	High speed digital CMOS divide-by-N frequency divider. , 2008, , .		8
30	A New Characterization and Calibration Method for 3-dB-Coupled On-Wafer Measurements. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1193-1200.	4.6	17
31	Marchand Balun Embedded Probe. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1207-1214.	4.6	13
32	A low-power CAM using a 12-transistor design cell. , 2007, , .		1
33	Embedded Jitter Measurement of High-speed I/O Signals. , 2007, , .		0
34	Integrated BiCMOS 10 GHz S-Parameter Module. Bipolar/BiCMOS Circuits and Technology Meeting, IEEE Proceedings of the, 2006, , .	0.0	4
35	IIP<3</inf> estimation from gain compression of RF power amplifiers. , 2005, , .		1
36	Role of Silver Doping in the Improvement of Electrical Properties of (Ba,Sr)TiO ₃ Thin Films. Materials Research Society Symposia Proceedings, 1999, 567, 463.	0.1	0